Product End-of-Life Disassembly Instructions

Product Category: Monitors and Displays

Marketing Name / Model
[List multiple models if applicable.]
HP EliteDisplay E190i 19-in 5:4 LED Backlit IPS Monitor

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm USB BD, IF BD, POWER BD, FK BD</td>
<td>4</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td></td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps Panel</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>Power BD only (C805)</td>
<td>1</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>USB cable, D-sub cable, DVI cable, Power cord</td>
<td>4</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing radioactive substances</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>
2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 SCREW DRIVER(PHILLIPS HEAD)</td>
<td>#2</td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Take Screw(x4) Off From Stand & Remove Stand
2. Remove Rear Cover From Display Head
3. Remove Front Cover From Display Head
4. Remove Rubber foot From Rear Cover
5. Remove Key Board Off From Chassis
6. Remove Lamp Cable & LVDS Cable Out of Panel
7. Take Screw(x4) Off From Chassis Cover & Remove Panel
8. Take Screw(x6) Off From P.C.B
9. Take Screw(x1) Off From USB
10. Take Screw(x7) Off From P.C.B
11. Remove BKT (Printed Circuit Assemblies>10cm*2
12. Remove Mylar From Chassis Cover & Remove USB BD From Chassis
13. LCD PANEL EXPLODE
14. Take Screw(*4)Off From Quick Release
15. Remove Quick Release off Stand Base
16. Remove the PET(AI Film) cover shield
17. Dismantle the case top ( Down)
18. Dismantle the case top (Right or Left )
19. Separate case top (push the case top because of damages on COF)
20. Dismantle the PCB
21. Remove the Conductive Tape
22. Remove the Board Assay
23. Remove the Guide Panel
24. Remove Optical Sheet
25. Remove Optical LGP
26. Disassembling Complete

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
HP E190i Disassembly Process

- Stone Zhang
- Mechanical Engineer
- Aug-12-2013
External Electric Cables Dissecting Process

1. Remove Cable From Display Head.
2. Dissecting To Complete.
Remove Stand from Display Head

1. Release the four screws for Stand to RC

2. Remove Stand from Display Head.
5. Remove Rear Cover from Display Head.
Remove Front Cover From Display Head

6. Remove Front Cover.

Remove F/K BD by hand
Remove Rubber foot From Rear Cover
Take Screw(*2) Off From Chassis Cover & Remove Panel

1. Remove connector from Panel
2. Remove four screws from Chassis
3. Peal off the Aluminum Tape from LVDS connector
4. Remove connector off from Panel.
5. Separate the Panel and Metal.
1. Take Screw(x7) Off From P.C.B
Take Screw(x1) Off From USB

1. Take Screw(x1) Off From USB then remove Cable from connector
Take Screw(x5) Off From P.C.B

1. Take Screw(x5) Off From P.C.B
Take Screw(x5) Off From P.C.B & Remove BKT (Printed Circuit Assemblies>10cm*2)
Remove Mylar From Chassis Metal
LCD PANEL EXPLODE

Step 1: Remove the PET (Al Film) cover shield

Step 2: Dismantle the case top (Down)

Step 3: Dismantle the case top (Right or Left)

Step 4: Separate case top (push the case top because of damages on COF)

Step 5: Dismantle the PCB

Step 6: Remove the Conductive Tape (1)
LCD PANEL EXPLODE

Step 6: Remove the Conductive Tape (2)

Step 7: Remove the Board Assay

Step 8: Remove the Guide Panel

Step 8: Remove Optical Sheet

Step 9: Remove Optical LGP

Disassembling Complete.
Electrolytic Capacitors Over 25mm High & Diameter Dissecting Process

1. Heats Up, Dissolved Tin Lead.
2. Takes Down The Capacitor.
3. Dissecting To Complete.
(Next Page Have Description)
Remove Lock pin
Remove Base

Take QR screws off